

QUESTTECH

Laser Conductor Removal (Ablation) for Electrical Isolation

Applications

General

- Modify Standard Microcircuit Packages to Custom Configuration inexpensively
- Isolation of up to 1000 M Ω
- Create Complex Pad Shapes
- No hard tooling charge or non-recurring engineering charge
- No tooling impact for design changes
- Economical small lot quantities or production runs

Types

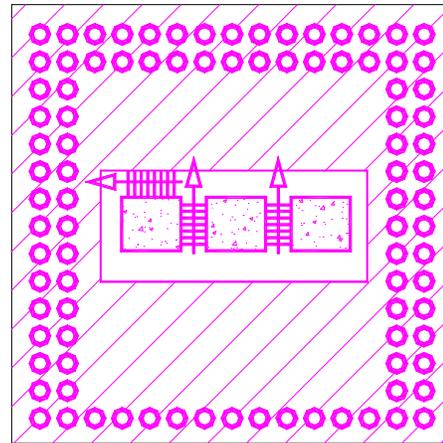
- Co-fired Packages
- Thick Film Packages
- Thin Film Packages

Uses

- Prototyping
- Short Run Production or Volume
- Removal of Plating Buss Bars

Materials

- Alumina and Beryllia (BeO) Packages
- Gold, Silver, Copper Or Nickel Conductors



Typical Buss Removal Application

Design Guidelines

Property	Nominal	Units
Smallest Feature	.002	Inches
Minimum Radius	.001	Inches
Feature Tolerances as cut	+/- .002	Inches
Minimum Distance to a Vertical Wall	.001	Inches
Maximum Working Size	6.0 x 6.0	Inches
Substrate Penetration	.002 to .006	Inches
Minimum Electrical Isolation	750	M Ω
Ultrasonic and other Cleaning Processes	Available	n/a

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